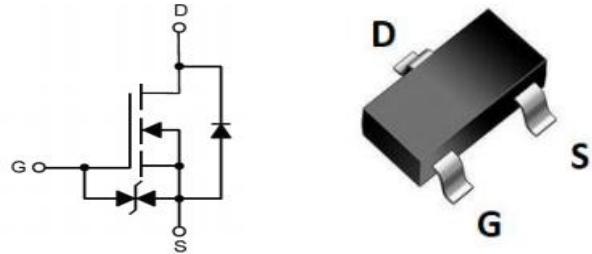


**SOT-323 60V N Channel ESD Protection 沟道带静电保护
MOS Field Effect Transistor 场效应管**



■Absolute Maximum Ratings 最大额定值

| Characteristic 特性参数 | Symbol 符号 | Rat 额定值 | Unit 单位 |
|--|--------------------------------|----------|--------------|
| Drain-Source Voltage 漏极-源极电压 | BV_{DSS} | 60 | V |
| Gate- Source Voltage 栅极-源极电压 | V_{GS} | ± 20 | V |
| Drain Current (continuous)漏极电流-连续 | I_D (at $T_A = 25^\circ C$) | 340 | mA |
| Drain Current (pulsed)漏极电流-脉冲 | I_{DM} | 800 | mA |
| Total Device Dissipation 总耗散功率 | P_D (at $T_A = 25^\circ C$) | 200 | mW |
| ESD Protected Up to 人体模式静电保护范围 | ESD(HBM) | 2.0 | kV |
| Thermal Resistance Junction-Ambient 热阻 | $R_{\theta JA}$ | 625 | $^\circ C/W$ |
| Junction/Storage Temperature 结温/储存温度 | T_J, T_{stg} | -55~150 | $^\circ C$ |

■Applications 应用/Marking 产品字标

Load Switch 负载开关
DC/DC Converter 电源转换
2N7002KW=72K

■ Electrical Characteristics 电特性

($T_A=25^\circ\text{C}$ unless otherwise noted 如无特殊说明, 温度为 25°C)

| Characteristic 特性参数 | Symbol 符号 | Min 最小值 | Typ 典型值 | Max 最大值 | Unit 单位 |
|--|--------------------------|------------|------------|------------|---------------|
| Drain-Source Breakdown Voltage 漏极-源极击穿电压($I_D=250\mu\text{A}, V_{GS}=0\text{V}$) | BV_{DSS} | 60 | — | — | V |
| Gate Threshold Voltage 栅极开启电压($I_D=1\text{mA}, V_{GS}=V_{DS}$) | $V_{GS(\text{th})}$ | 1 | 1.3 | 2.5 | V |
| Zero Gate Voltage Drain Current 零栅压漏极电流($V_{GS}=0\text{V}, V_{DS}=48\text{V}$) | I_{DSS} | — | — | 1 | μA |
| Gate Body Leakage 栅极漏电流($V_{GS}=\pm20\text{V}, V_{DS}=0\text{V}$) | I_{GSS} | — | — | ±10 | μA |
| Static Drain-Source On-State Resistance 静态漏源导通电阻($I_D=500\text{mA}, V_{GS}=10\text{V}$) ($I_D=200\text{mA}, V_{GS}=4.5\text{V}$) | $R_{DS(\text{ON})}$ | — | 0.9 1.1 | 5 5.3 | Ω |
| Diode Forward Voltage Drop 内附二极管正向压降($I_{SD}=300\text{mA}, V_{GS}=0\text{V}$) | V_{SD} | — | — | 1.5 | V |
| Input Capacitance 输入电容 ($V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$) | C_{ISS} | — | 40 | — | pF |
| Common Source Output Capacitance 共源输出电容($V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$) | C_{OSS} | — | 30 | — | pF |
| Reverse Transfer Capacitance 反馈电容($V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$) | C_{RSS} | — | 10 | — | pF |
| Total Gate Charge 棚极电荷密度 ($V_{DS}=30\text{V}, I_D=300\text{mA}, V_{GS}=10\text{V}$) | Q_g | — | 1.6 | — | nC |
| Gate Source Charge 棚源电荷密度 ($V_{DS}=30\text{V}, I_D=300\text{mA}, V_{GS}=10\text{V}$) | Q_{gs} | — | 0.5 | — | nC |
| Gate Drain Charge 棚漏电荷密度 ($V_{DS}=30\text{V}, I_D=300\text{mA}, V_{GS}=10\text{V}$) | Q_{gd} | — | 0.3 | — | nC |
| Turn-ON Delay Time 开启延迟时间 ($V_{DS}=30\text{V} I_D=300\text{mA}, R_{\text{GEN}}=6 \Omega, V_{GS}=10\text{V}$) | $t_{d(\text{on})}$ | — | 10 | — | ns |
| Turn-ON Rise Time 开启上升时间 ($V_{DS}=30\text{V} I_D=300\text{mA}, R_{\text{GEN}}=6 \Omega, V_{GS}=10\text{V}$) | t_r | — | 30 | — | ns |
| Turn-OFF Delay Time 关断延迟时间 ($V_{DS}=30\text{V} I_D=300\text{mA}, R_{\text{GEN}}=6 \Omega, V_{GS}=10\text{V}$) | $t_{d(\text{off})}$ | — | 20 | — | ns |
| Turn-OFF Fall Time 关断下降时间 ($V_{DS}=30\text{V} I_D=300\text{mA}, R_{\text{GEN}}=6 \Omega, V_{GS}=10\text{V}$) | t_f | — | 80 | — | ns |

■Typical Characteristic Curve 典型特性曲线

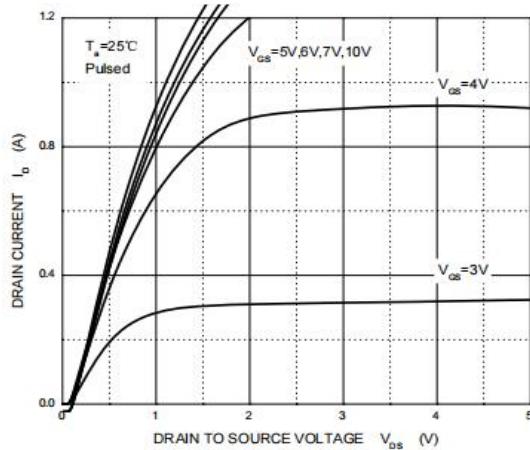


Figure 1: Output Characteristics

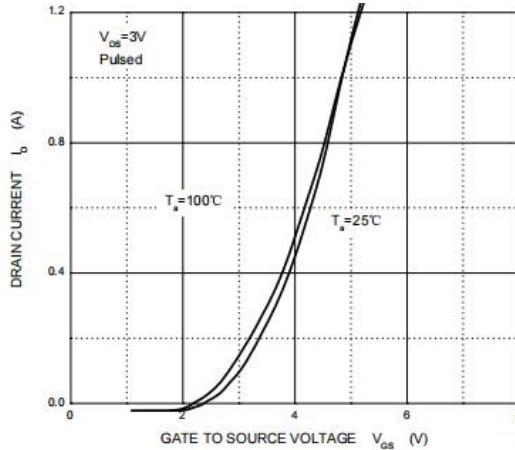


Figure 2: Transfer Characteristics

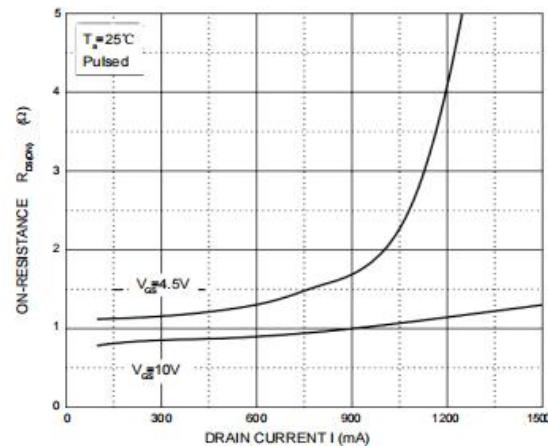


Figure 3: On-Resistance vs. Drain Current

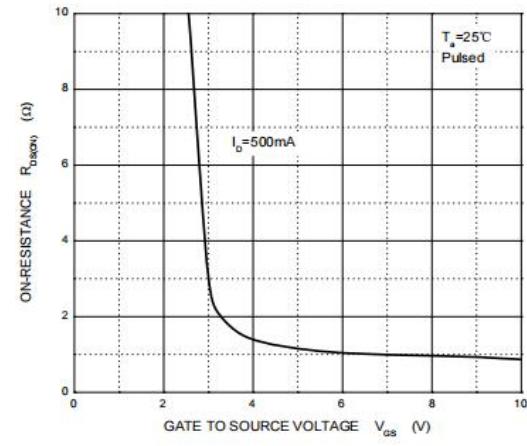


Figure 4: On-Resistance vs. V_{GS}

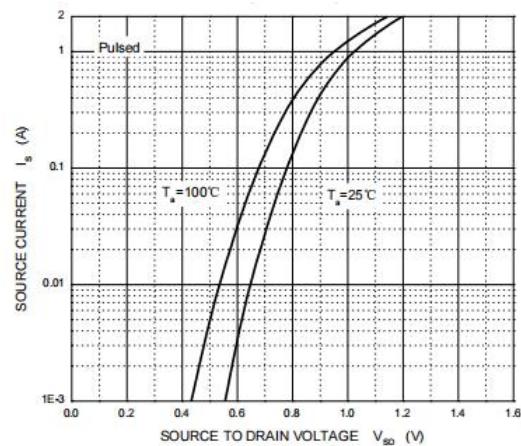


Figure 5: Diode Characteristics

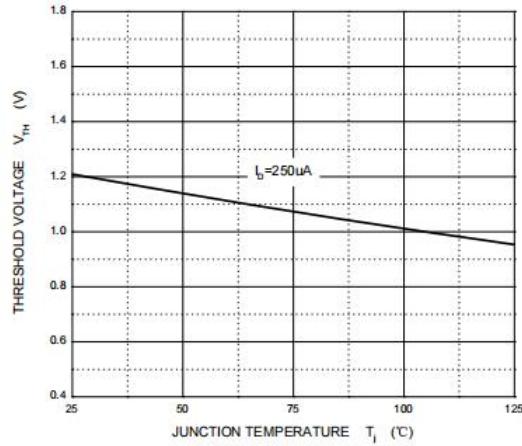
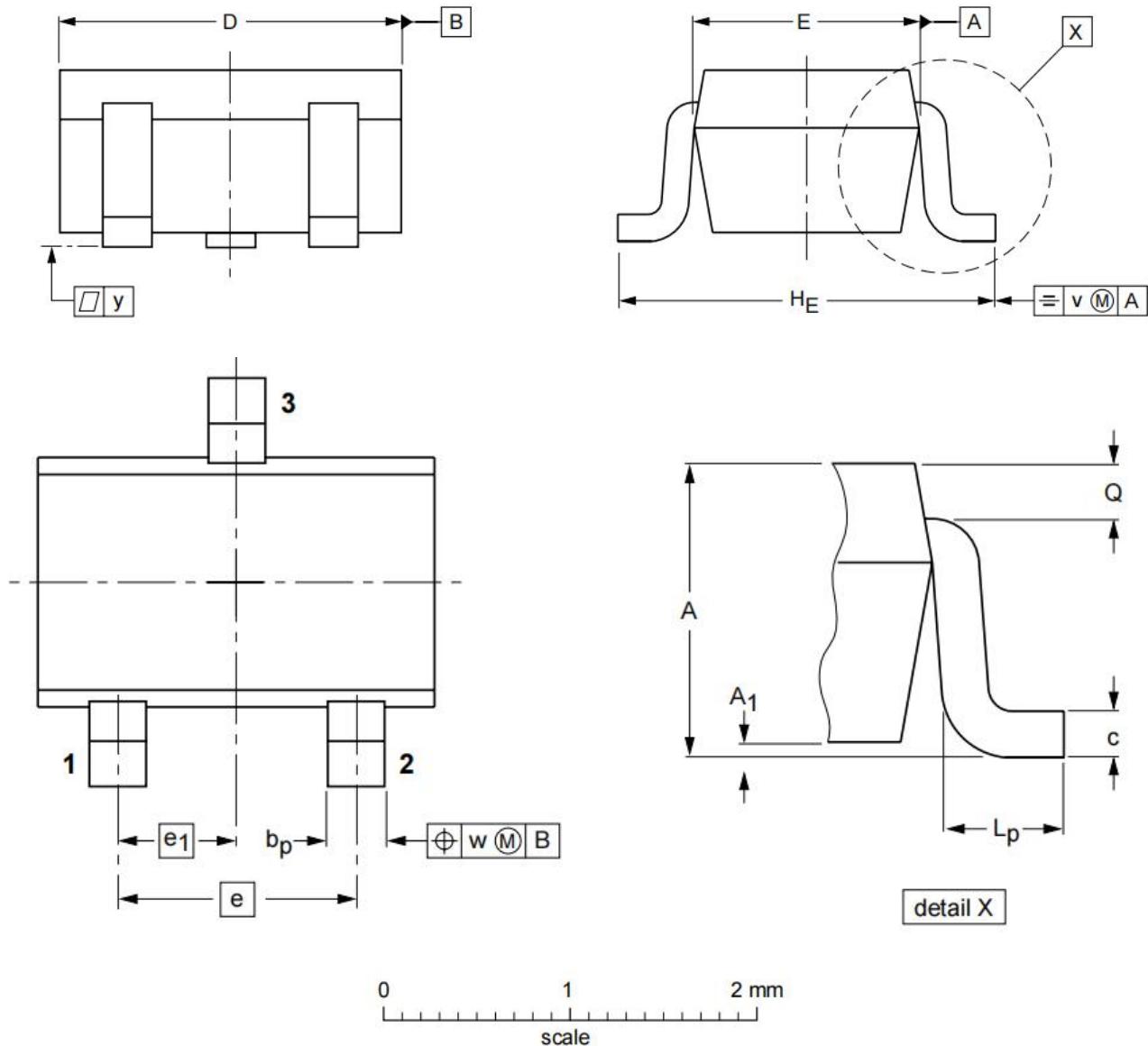


Figure 6: Threshold Voltage Characteristics

■ Dimension 外形封装尺寸



DIMENSIONS (mm are the original dimensions)

| UNIT | A | A ₁ max | b _p | c | D | E | e | e ₁ | H _E | L _p | Q | v | w |
|------|------------|-----------------------|----------------|--------------|------------|--------------|-----|----------------|----------------|----------------|--------------|-----|-----|
| mm | 1.1 0.8 | 0.1 | 0.4 0.3 | 0.25 0.10 | 2.2 1.8 | 1.35 1.15 | 1.3 | 0.65 | 2.2 2.0 | 0.45 0.15 | 0.23 0.13 | 0.2 | 0.2 |